

Ball Grid Array (BGA) Package Market: Global Share, Size, Trends and Growth Analysis Forecast to 2019-2024

Ball Grid Array (BGA) Package -Market Demand, Growth, Opportunities and Analysis Of Top Key Player Forecast To 2024

PUNE, MAHARASHTRA, INDIA, May 21, 2019 /EINPresswire.com/ -- [Ball Grid Array \(BGA\) Package Industry](#)

Description

A Ball Grid Array or BGA package is a form of surface mount technology, or SMT package that is being used increasingly for integrated circuits.. The Ball Grid Array, BGA, uses a different approach to the connections to that used for more conventional surface mount connections. Other packages such as the quad flat pack, QFP, used the sides of the package for the connections. This meant that there was limited space for the pins which had to be spaced very closely and made much smaller to provide the required level of connectivity. The Ball Grid Array, BGA, uses the underside of the package, where there is a considerable area for the connections.

The Ball Grid Array, BGA package was developed out of the need to have a more robust and convenient package for integrated circuits with large numbers of pins. With the levels of integration rising, some integrated circuits had in excess of 100 pins.

In 2018, the global Ball Grid Array (BGA) Package market size was xx million US\$ and it is expected to reach xx million US\$ by the end of 2025, with a CAGR of xx% during 2019-2025.

This report focuses on the global Ball Grid Array (BGA) Package status, future forecast, growth opportunity, key market and key players. The study objectives are to present the Ball Grid Array (BGA) Package development in United States, Europe and China.

The key players covered in this study

Intel
NexLogic Technologies
Texas Instruments
Palomar Technologies
Micro Systems Technologies
Sonix
Advanced Interconnections Corp

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Market segment by Type, the product can be split into
Common BGA package
Flip Chip BGA Package

Market segment by Application, split into
PCBs
Other

Market segment by Regions/Countries, this report covers
United States
Europe
China
Japan
Southeast Asia
India
Central & South America

The study objectives of this report are:

To analyze global Ball Grid Array (BGA) Package status, future forecast, growth opportunity, key market and key players.

To present the Ball Grid Array (BGA) Package development in United States, Europe and China.

To strategically profile the key players and comprehensively analyze their development plan and strategies.

To define, describe and forecast the market by product type, market and key regions.

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